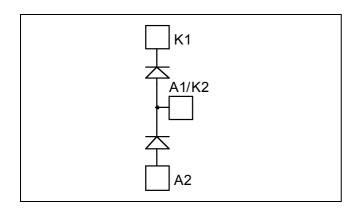


Diode Phase leg Power Module

$$V_{RRM} = 1200V$$

 $I_C = 400A$ @ $Tc = 60$ °C



A1/K2

Α2

Application

- Anti-Parallel diode
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- **RoHS Compliant**

Absolute maximum ratings

Symbol	Parameter				Max ratings	Unit
V_R	Maximum DC reverse Voltage	Maximum DC reverse Voltage			1200	V
V_{RRM}	Maximum Peak Repetitive Revers	e Voltage			1200	V
$I_{F(AV)}$	Maximum Average Forward	D 4		$T_C = 25^{\circ}C$	470	
	Current	Duty cycle	e = 50%	$T_C = 60$ °C	400	Α
I _{F(RMS)}	RMS Forward Current	Duty cycle = 50%		$T_C = 45^{\circ}C$	500	Λ
I_{FSM}	Non-Repetitive Forward Surge Cu	rrent	8.3ms	$T_C = 45^{\circ}C$	3000	

These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
V_{F}	Diode Forward Voltage	$I_F = 400A$			2.4	3.0	
		$I_F = 600A$			2.7		V
		$I_F = 400A$	$T_{j} = 125^{\circ}C$		1.8		
I_{RM}	Maximum Reverse Leakage Current	$V_R = 1200V$ $T_i = 25^{\circ}C$ $T_j = 125^{\circ}C$	$T_i = 25^{\circ}C$			250	4
			$T_{j} = 125^{\circ}C$			1000	μΑ
C_{T}	Junction Capacitance	$V_R = 1200V$			440		pF

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
t_{rr}	Reverse Recovery Time	$I_F=1A, V_R=30V$ $di/dt = 400A/\mu s$	$T_j = 25$ °C		45		ns
t _{rr}	Reverse Recovery Time	$T_j = 25^{\circ}C$		385		ns	
·rr			$T_j = 125$ °C		480		110
Q _{rr}	Reverse Recovery Charge	$I_F = 400A$ $V_R = 800V$ $di/dt = 800A/\mu s$	$T_j = 25^{\circ}C$		4.2		μС
Qrr	Reverse Recovery Charge		$T_{j} = 125^{\circ}C$		20.9		
T	Reverse Recovery Current		$T_j = 25^{\circ}C$		24		A
I_{RRM}	Reverse Recovery Current		$T_{j} = 125^{\circ}C$		76		
t_{rr}	Reverse Recovery Time	$\begin{split} I_F &= 400A \\ V_R &= 800V \\ di/dt &= 4000A/\mu s \end{split}$			210		ns
Qrr	Reverse Recovery Charge		$T_j = 125$ °C		38		μС
I_{RRM}	Reverse Recovery Current				280		A

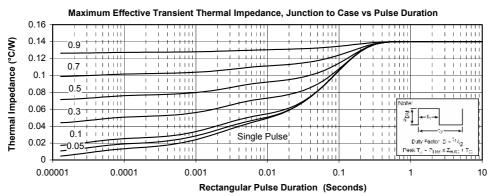
Thermal and package characteristics

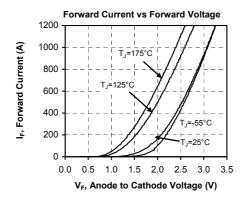
Symbol	Characteristic			Min	Тур	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance					0.14	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range			-40		175	°C
T _{STG}	Storage Temperature Range			-40		125	
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
	Mounting torque	For terminals	M5	2		3.5	11.111
Wt	Package Weight					300	g

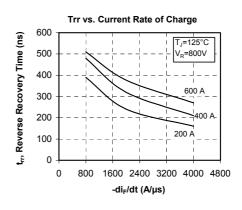
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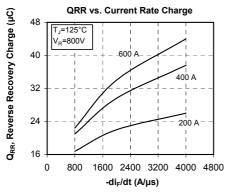


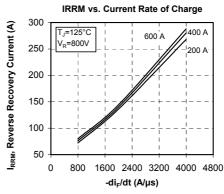
Typical Performance Curve

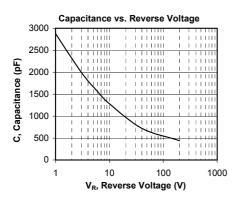


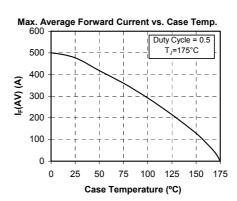






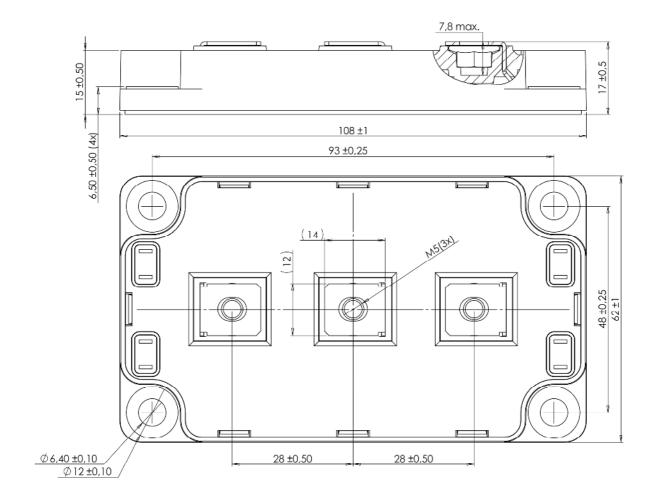








SP6 Package outline (dimensions in mm)





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